

Abstract

This invention relates to a photo- or heat-curable resin composition which yields a cured product with minimal cracking and high reliability. The resin composition of this invention comprises 100 parts by weight of (A) photo- or heat-polymerizable unsaturated compound composed of a polycarboxylic acid adduct of bisphenol-epoxy (meth)acrylate, 10-100 parts by weight of (B) alkylene oxide-modified product of (meth)acrylate or oligomers thereof, 0-50 parts by weight of (C) compound containing epoxy group and 0-50 parts by weight of (D) photopolymerization initiator or sensitizer. The composition exhibits high heat resistance and good microfabrication quality and is useful as a peripheral material of electronic parts such as semiconductor devices by the build-up process, for example, as a material for forming insulation layers in multilayer printed wiring boards.